

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

- 1-26. (canceled)
27. (original) A system comprising:  
a chuck to hold a wafer, the wafer having a front side attached to a tape;  
an imaging sensor to obtain a scribe pattern on the front side through the tape; and  
a laser mounted above the chuck to mark an alignment pattern on a back side of the wafer  
based on the scribe pattern.
28. (original) The system of claim 27 wherein the chuck holds the wafer front side  
up.
29. (original) The system of claim 26 wherein the imaging sensor is mounted above  
the wafer.
30. (original) The system of claim 27 further comprising:  
a flipping mechanism to turn up the back side of the wafer.
31. (original) The system of claim 25 wherein the chuck holds the wafer back side  
up.
32. (original) The system of claim 29 wherein the imaging sensor is mounted  
underneath the wafer.
33. (original) The system of claim 25 wherein the laser emits a laser beam from the  
laser to etch the alignment pattern on the back side, the alignment pattern being directly opposite  
to the scribe pattern.
34. (original) The system of claim 25 further comprising:

a processing unit to recognize the alignment pattern on the back side of the wafer.

35. (original) The system of claim 32 further comprising:

a cutter to cut the back side of the wafer based on the alignment pattern.

36. (original) The system of claim 32 wherein the processing unit recognizes the scribe pattern and saves the scribe pattern in a memory.